

20V Dual N-Channel Enhancement Mode MOSFET

Description	Schematic diagram
<p>The CP4810QR-N uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge.</p> <p>This device is suitable for high side switch in SMPS and general purpose applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ◆ $V_{DS} = 20V$, $ID = 30A$ ◆ $R_{DS(ON)} = 8.7m\Omega$ (typical) @ $VGS = 4.5V$ ◆ $R_{DS(ON)} = 11.5m\Omega$ (typical) @ $VGS = 2.5V$ ◆ Excellent gate charge $\times R_{DS(ON)}$ product(FOM) ◆ Very low on-resistance $R_{DS(ON)}$ ◆ 150 °C operating temperature ◆ Pb-free lead plating <p>Application</p> <ul style="list-style-type: none"> ◆ DC/DC Converter ◆ Ideal for high-frequency switching and synchronous rectification <p>Package</p> <ul style="list-style-type: none"> ◆ PDFN3*3-8L 	<p>Marking and pin assignment</p> <p>XXXX—Quality Code</p>

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP4810QR-N-G	-55°C to +150°C	PDFN3*3-8L	5000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit	
Drain-source voltage	V_{DS}	20	V	
Gate-source voltage	V_{GS}	± 12	V	
Drain Current-Continuous (Silicon Limited)	$T_A = 25^\circ C$	I_D	30	
Pulsed Drain Current (Package Limited)	$T_A = 75^\circ C$		18	
Single pulse avalanche energy	E_{AS}	92	A	
Maximum power dissipation	$T_A = 25^\circ C$	P_D	40	
	$T_A = 75^\circ C$		8	

Operating junction Temperature range	T _j	-55—150	°C
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	20	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.4	0.65	1	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =10A	-	8.7	11.5	mΩ
		V _{GS} =2.5V, I _D =8A	-	11.5	15	
Forward transconductance	g _f s	V _{DS} =10V, I _D =10A	-	35	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =10V, V _{GS} =0V f=1.0MHz	-	965	-	pF
Output capacitance	C _{OSS}		-	186	-	
Reverse transfer capacitance	C _{RSS}		-	174	-	
Gate resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1.0MHz	-	2.5	3.5	Ω
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DS} =10V V _{GS} =5V R _L =1.5Ω R _{GEN} =3Ω	-	22	-	ns
Rise time	t _r		-	34	-	
Turn-off delay time	t _{D(OFF)}		-	51	-	
Fall time	t _f		-	17	-	
Total gate charge	Q _g	V _{DS} =10V, I _D =10A V _{GS} =5V	-	14.2	-	nC
Gate-source charge	Q _{gs}		-	2.7	-	
Gate-drain charge	Q _{gd}		-	3.2	-	

Thermal Characteristics

Thermal Resistance junction-to ambient	R _{th JA}	52	°C/W
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Typical Performance Characteristics

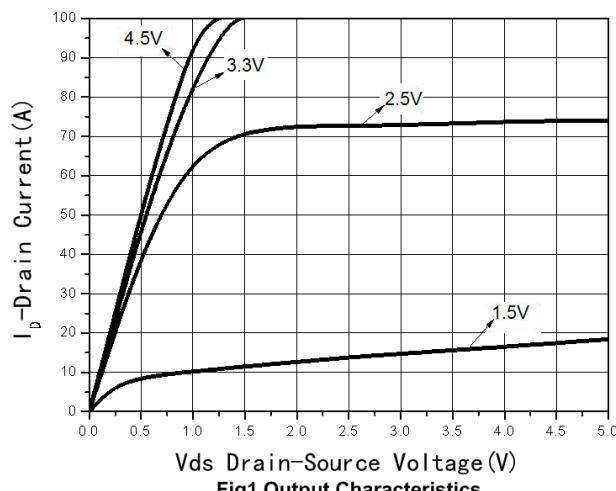


Fig1 Output Characteristics

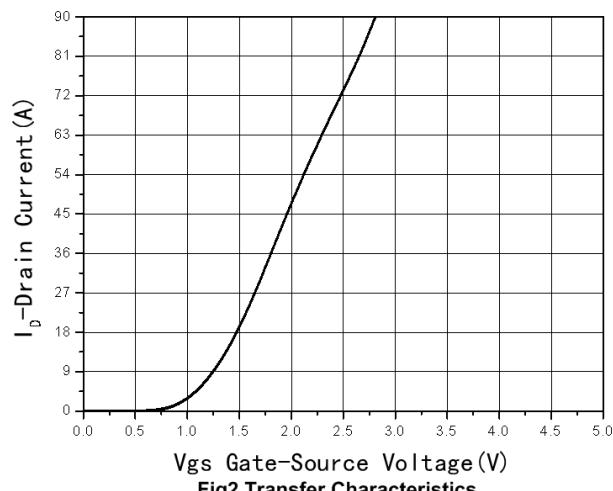


Fig2 Transfer Characteristics

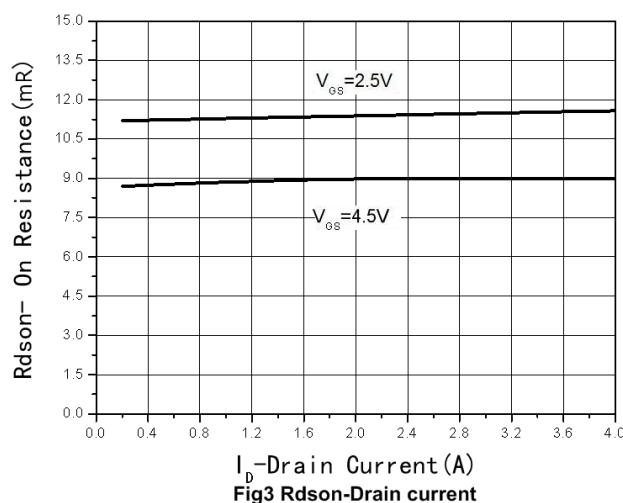


Fig3 Rdson-Drain current

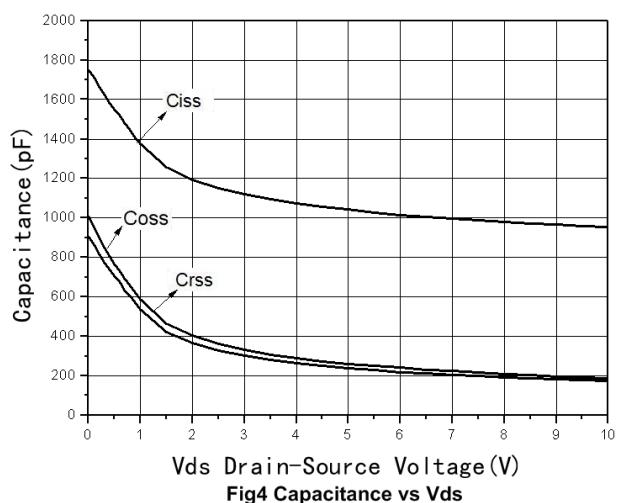


Fig4 Capacitance vs Vds

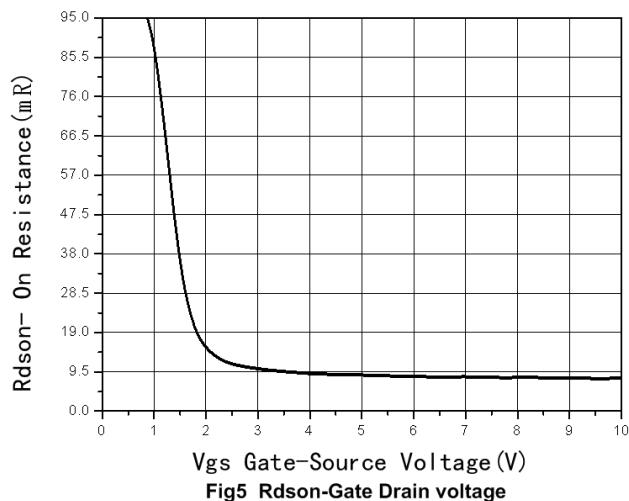


Fig5 Rdson-Gate drain voltage

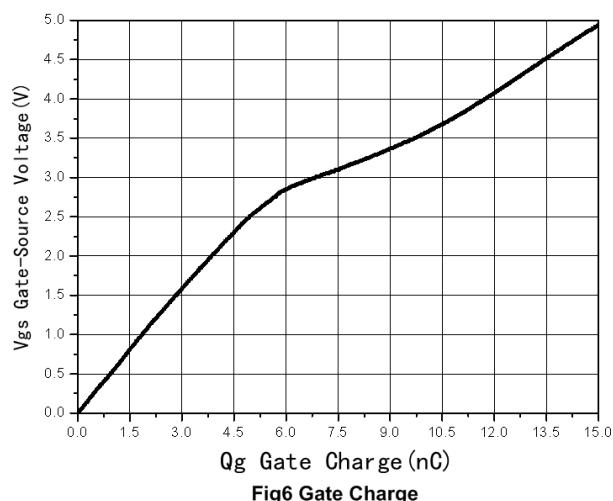
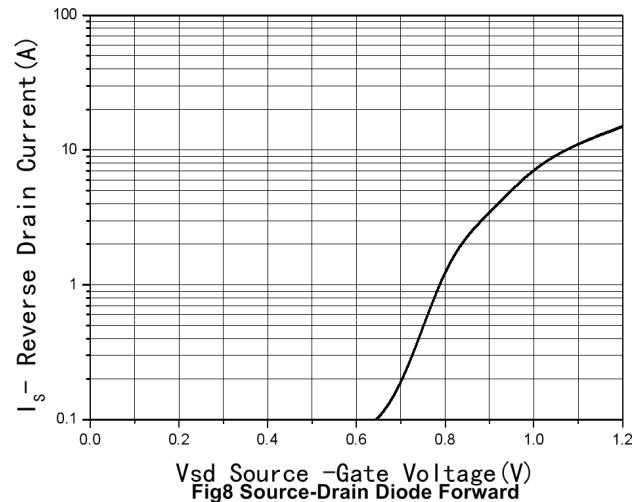
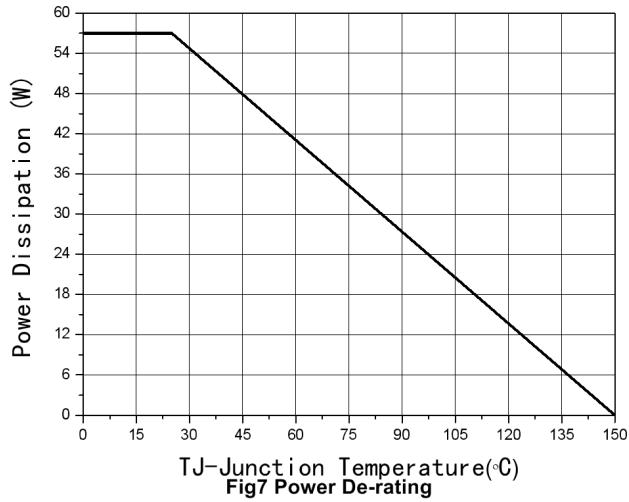
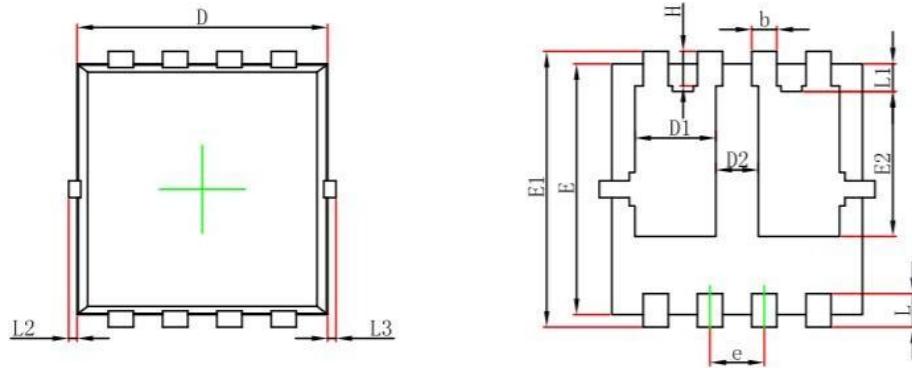


Fig6 Gate Charge



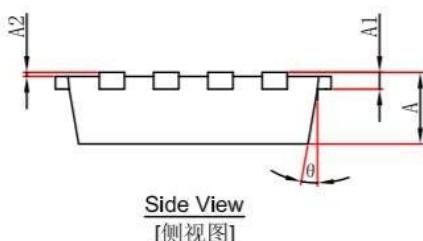
Package Information

- PDFN3*3-8L



Top View
[顶视图]

Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152 REF.		0.006 REF.	
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°